## Claims

- [c1] 1.A method of forming a printed circuit board, the method comprising the steps of: providing a substrate comprising a seed layer formed by electroless plating; forming a masking layer on said seed layer to provide first regions of exposed seed layer; forming a circuit pattern on said first regions of exposed seed layer by electrolytic plating; removing said masking layer to expose second regions of said seed layer; and etching said exposed second regions of said seed layer with an etching liquid, said etching liquid at a temperature less than about 15 degrees Celcius.
- [c2] 2.The method of claim 1, wherein the temperature of said etching liquid is about 5°C to about 10°C.
- [c3] 3.The method of claim 1, wherein said masking layer comprises photoresist.
- [c4] The method of claim 1, wherein said seed layer and said circuit pattern comprise copper.

- [c5] The method of claim 1, wherein a distance between confronting portions of said circuit pattern is about 150µm or less.
- [c6] The method of claim 1, wherein said seed layer and said circuit pattern are formed by copper plating.
- [c7] The method of claim 1, wherein said etching liquid comprises an acid.
- [c8] The method of claim 7, wherein said acid comprises an H  $_2O_2-H_2SO_4$  aqueous solution.
- [09] The method of claim 1, wherein said substrate is dipped in said etching liquid within a dip bath.